ABSTRACT

INTEGRATED CIRCUIT MANUFACTURE

A lead frame or PCB (e.g. a ball grid array) has an array of IC package mounts 8a-c. At the head of each column an inclined line of reject markers 10a-c is provided, one for each IC package mount in the column. Each reject marker 10 comprises an island joined to the remainder of the substrate by short tie-bars. The islands are broken out to indicate the corresponding IC mount or an IC package mounted there is a reject.

Fig. 2